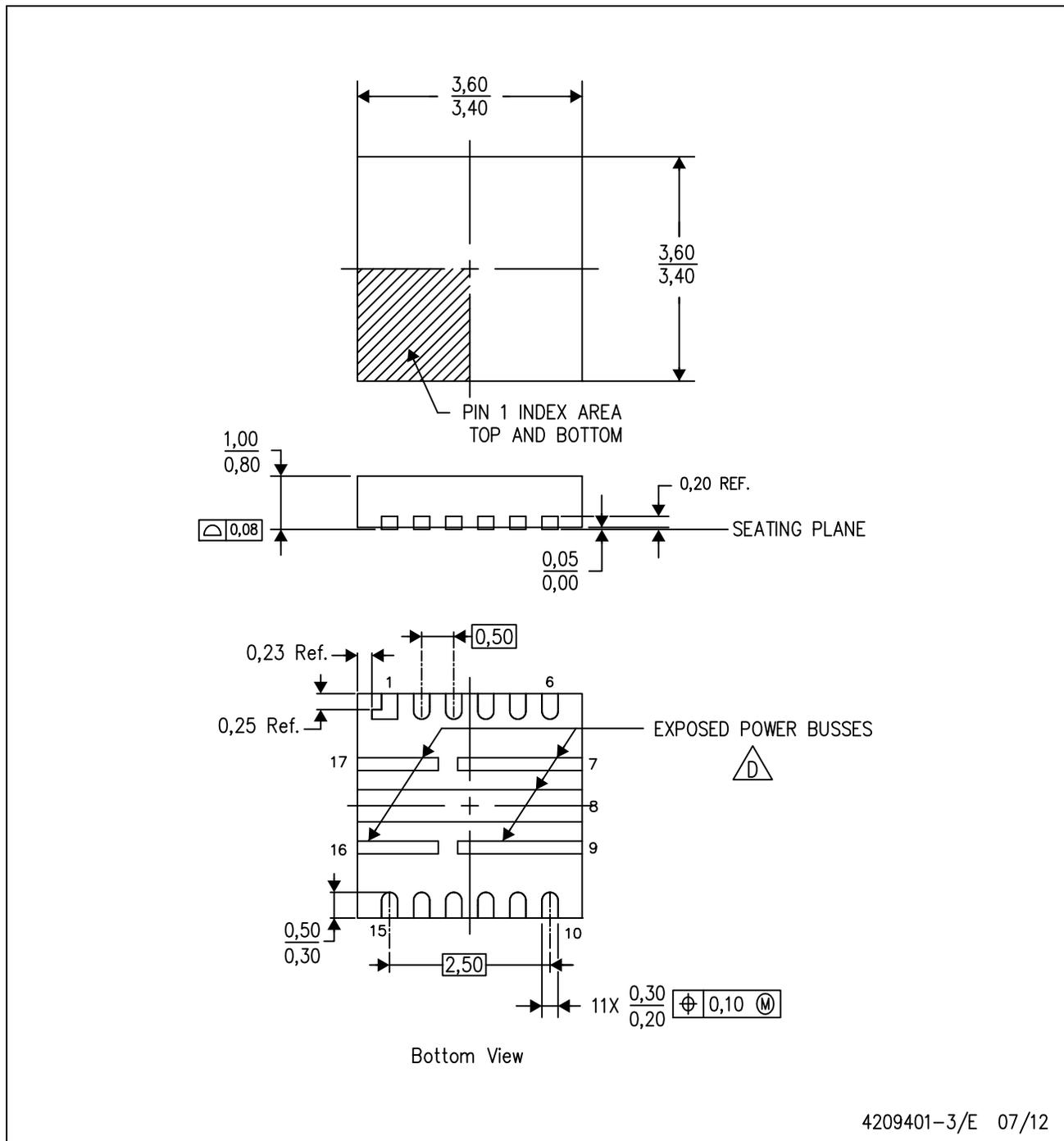


MECHANICAL DATA

RUW (S-PVQFN-N17)

PLASTIC QUAD FLATPACK NO-LEAD



4209401-3/E 07/12

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Quad Flatpack, No-leads (QFN) package configuration.
 - See the Product Data Sheet for details regarding the exposed power buss dimensions.
 - E. RoHS exempt flip chip application. Internal solder joints may contain Pb.
 - F. Exposed terminals are Pb-free

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